

**METHOD FOR MAKING ELECTRONIC MODULES WITH BALL CONNECTOR
OR WITH INTEGRATED PREFORMS CAPABLE OF BEING SOLDERED ON A
PRINTED CIRCUIT AND IMPLEMENTING DEVICE**

ABSTRACT

The invention concerns a method for producing electronic modules with ball connector (7) or integrated preforms capable of being soldered on a printed circuit (3) and a device for implementing said method. The invention concerns a method for producing electronic modules in the form of ball housings combining a ball grid array (7) or geometrically identical preforms for interconnecting or shielding and surface-mounted components (2) on the same surface of a substrate (1), thereby enabling said module to be directly connectable by soldering on a printed circuit (3). The balls (7) and the components (2) are transferred in one single step onto the substrate (1) by means of a gripping device adapted to the topography of the module to be produced.

SEARCHED
INDEXED
MAILED
FILED